- Member of the Texas Instruments Widebus™ Family
- 25-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

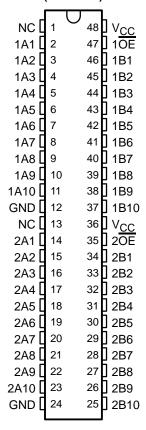
description

The SN74CBTR16861 provides 20 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one dual 10-bit switch with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

The device has equivalent $25-\Omega$ series resistors to reduce signal-reflection noise. This eliminates the need for external terminating resistors.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tube	SN74CBTR16861DL	CBTR16861
4000 1- 0500	330F - DL	Tape and reel	SN74CBTR16861DLR	CBIKI0001
-40°C to 85°C	TSSOP – DGG	Tape and reel	SN74CBTR16861DGGR	CBTR16861
	TVSOP - DGV	Tape and reel	SN74CBTR16861DGVR	CZ861

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 10-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
Н	Disconnect

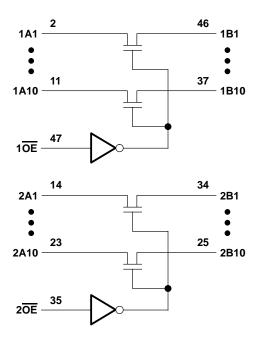


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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DGG package	70°C/W
•	DGV package	58°C/W
	DL package	63°C/W
Storage temperature range, T _{stq}		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CONDITIONS					UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
Ţ.,		$V_{CC} = 0$,	V _I = 5.5 V				10	^
l II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ
Icc		$V_{CC} = 5.5 \text{ V},$	I _O = 0,	$V_I = V_{CC}$ or GND			3	μΑ
Δl _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
Ci	Control inputs	$V_I = 3 V \text{ or } 0$				3.5		pF
C _{io(OFF}	=)	$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA	20	37	50	
ron§			\/ 0	I _I = 64 mA	20	33	47	Ω
		V _C C = 4.5 V	V _I = 0	I _I = 30 mA	20	33	47	
			V _I = 2.4 V,	I _I = 15 mA	20	35	48	

[†] All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

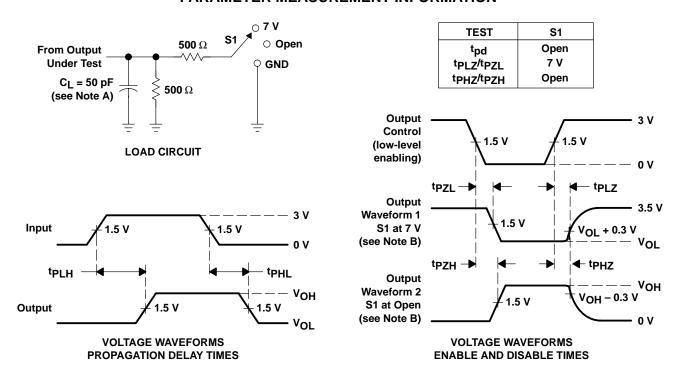
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		VCC =	UNIT	
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	
$t_{pd}\P$	A or B	B or A		1.25		1.25	ns
t _{en}	ŌĒ	A or B	3.1	9	2.7	8.6	ns
^t dis	ŌĒ	A or B	2.7	6.3	2.3	6.9	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74CBTR16861DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTR16861DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTR16861DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTR16861DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTR16861DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTR16861DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTR16861DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTR16861DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTR16861DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTR16861DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

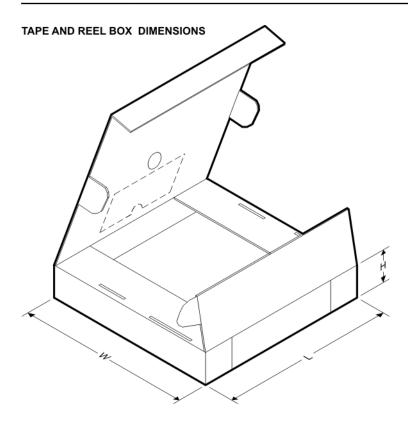
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTR16861DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74CBTR16861DGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1
SN74CBTR16861DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1





*All dimensions are nominal

7 til dillionolollo alo nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTR16861DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74CBTR16861DGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0
SN74CBTR16861DLR	SSOP	DL	48	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

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